

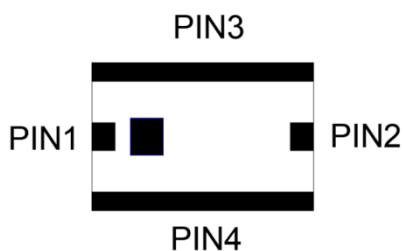
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

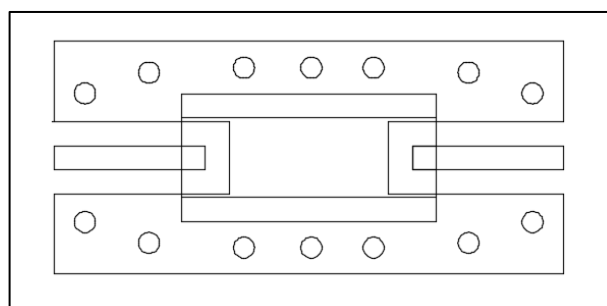
NO.	Parameter		SPC
1	Frequency (MHz)		1400-2400
2	Insertion Loss (dB) @25℃	1400-2400MHz	≤3.0
3	Ripple (dB)	1400-2400MHz	≤1.7
4	Attenuation (dB)	DC-1080MHz	≥50
		2670-2800MHz	≥45
		2800-5000MHz	≥49
5	VSWR		≤1.8
6	In/Output Impedance (Ω)		50
7	Power		2W
Operating & Storage Condition (Component) Operation Temperature Range: -40℃ ~ +85℃ Storage Temperature Range: -40℃~ +85℃			
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 ℃ Humidity: 30 to 70% relative humidity			

Construction

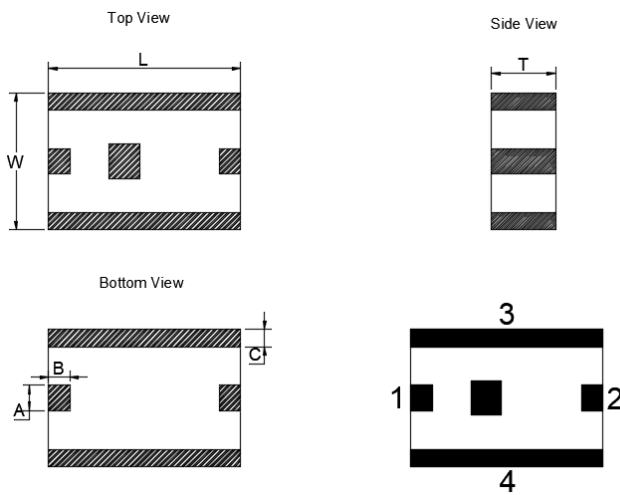


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

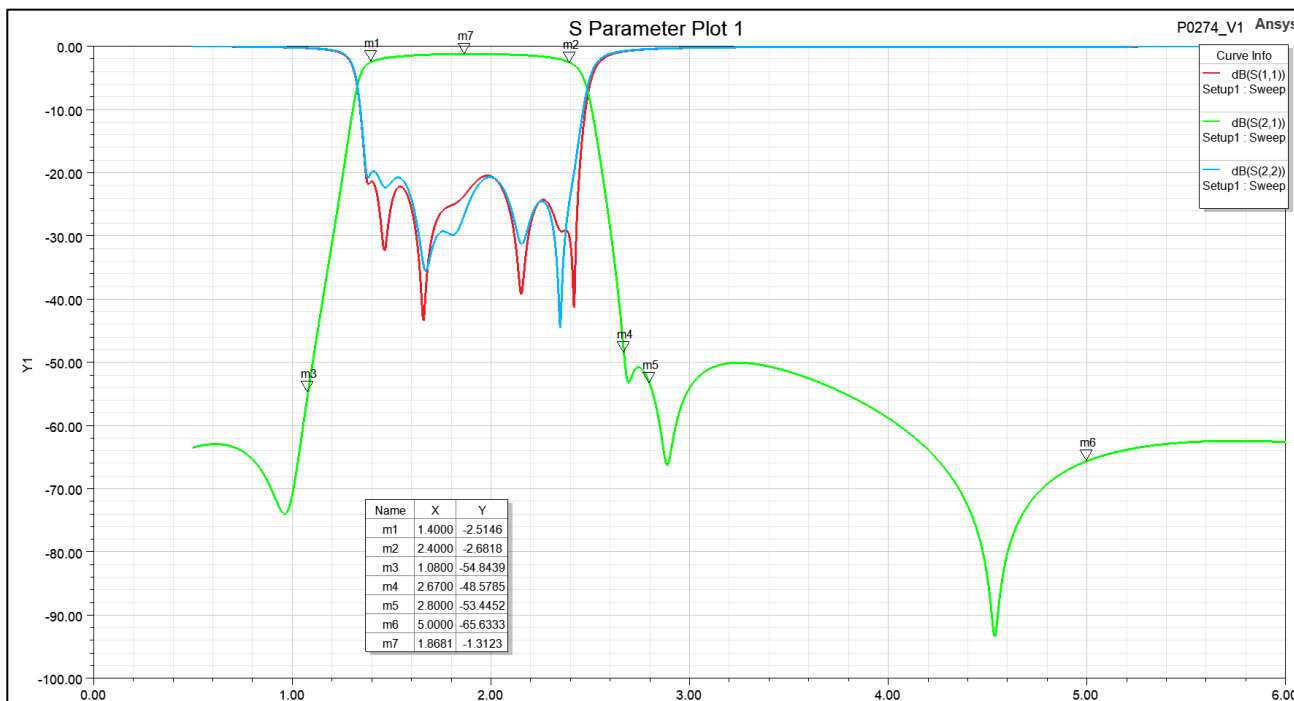
Mounting Considerations



Dimensions

Figure	Symbol	Dimension (mm)
 Top View: Length L, Width W. Side View: Thickness T. Bottom View: Dimensions A, B, C, and port locations 1, 2, 3, 4.	L	4.80 ± 0.20
	W	3.20 ± 0.20
	T	1.20 ± 0.20
	A	0.60 ± 0.10
	B	0.40 ± 0.10
	C	0.40 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.